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The New Swiss Photonics Integration Center (Swiss PIC)

The Federal Department of Economic Affairs, Education and Research (EAER) and the AM-TTC Alliance, the umbrella organization of technology transfer centers in the field of Advanced Manufacturing (AM) technologies, decided to fund a new center for photonics integration, [see AM-TTC announcement](#).



Photo provided by Polariton Technologies

With the ever-increasing demand for photonic systems in existing and future markets including optical communications, sensing, quantum computing, autonomous driving, AI, AR/VR, medical, and many others, the **complexity of photonic packaging** is also increasing. Common challenges for Swiss industry, especially start-ups and SMEs include assembly & packaging, testing and qualification and therefore support in these areas is crucial.

The newly established **Swiss Photonics Integration Center (Swiss PIC)** addresses these needs by providing precision assembly and packaging solutions for photonics systems. The complete packaging offering - including optical, electrical, thermal, and mechanical technology - ensures a controlled interfacing of photonic systems with the environment. Building upon a long history of precision engineering in Switzerland, the photonics packaging center offers the highest standards in terms of quality and precision. It provides customers with packaging services covering prototyping as well as series production. The center located in the [Switzerland Innovation Park InnovAare](#) next to PSI and will invest in qualified industrialized processes, high-tech machinery, and operate a qualified piloting and production line over time in Park InnovAare.

Founding partners of the center include Swiss Photonics, Ligentec, Polariton Technologies, Ostschweizer Fachhochschule and Paul Scherrer Institut.

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